(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
9 January 2014 (09.01.2014)

WIPO | PCT

(10) International Publication Number
WO 2014/006546 A3

(51) **International Patent Classification**:
G09G 1/02 (2006.01) ***C09K 3/14*** (2006.01)
G09G 1/14 (2006.01)

(21) **International Application Number**:
PCT/IB2013/055273

(22) **International Filing Date**:
27 June 2013 (27.06.2013)

(25) **Filing Language**: English

(26) **Publication Language**: English

(30) **Priority Data**:
12175333.9 6 July 2012 (06.07.2012) EP

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(81) **Designated States** *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) **Designated States** *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report (Art. 21(3))*

— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments (Rule 48.2(h))*

(88) **Date of publication of the international search report**:
27 February 2014

WO 2014/006546 A3

(54) **Title**: CHEMICAL MECHANICAL POLISHING COMPOSITION COMPRISING NON-IONIC SURFACTANT AND AROMATIC COMPOUND COMPRISING AT LEAST ONE ACID GROUP

(57) **Abstract**: A chemical mechanical polishing composition comprising: (A) inorganic particles, organic particles, or a mixture or composite thereof, wherein the particles are cocoon-shaped, (B) a non-ionic surfactant, (C) an aromatic compound comprising at least one acid group, or a salt thereof, and (M) an aqueous medium. A process for the manufacture of semiconductor devices comprising the chemical mechanical polishing of a substrate in the presence of a CMP composition and the use of CMP composition in the semiconductor industry are also provided.